

标 记 MARK	ECN编号/变更内容 ECN NO/DEFINITION	修 改 REVISE	日 期 DATE	核 准 APPROVE

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND

NOTE:

1.MATERIAL SPECIFICATION:
1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC
2.CONTACTS:COPPER ALLOY
3.MID PLATE: STAINLESS STEEL
4.INSIDE SHELL: STAINLESS STEEL
5.OUTSIDE SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:
2-1.CONTACTS:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
GOLD FLASH PLATING ON SOLDER AREA
2-2.INSIDE SHELL OR OUTSIDE SHELL:
Ni 30u" MIN. UNDER PLATED OVER ALL.

3.MECHANICAL PERFORMANCE,
3-1.INSERTION FORCE: 0.5~2.0kgf.
3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,
4-1. CURRENT RATING: 5A
VOLTAGE RATING: 20V
4-2.INSULATION RESISTANCE: 100MΩ MIN
4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
4-4.LOW CONTACT RESISTANCE: INITIAL 40MΩ
AFTER 50MΩ

5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -30℃~+80℃.

6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260℃.

3	外壳	不锈钢	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	
序号	品名	材质	电镀/颜色	备注



深圳市虹成电子有限公司

品名
TITLE

TYPE-C母座

料号
PART NO

HC-TYPE-C-16P-032D

GENERAL TOLERANCES
(UNLESS SPECIFIED)

比列
SCALE

1:1

单位
UNIT

MM

张数
PART NO

1 OF 1

版本
REV

A

制图
DRAW

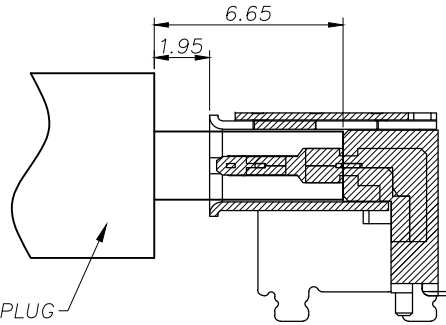
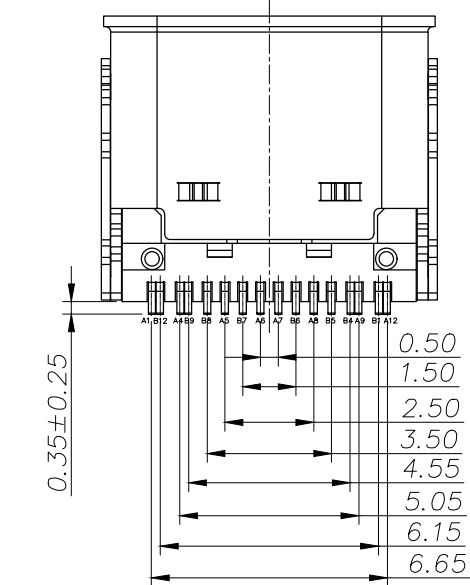
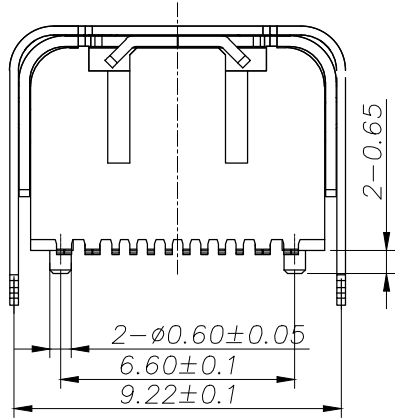
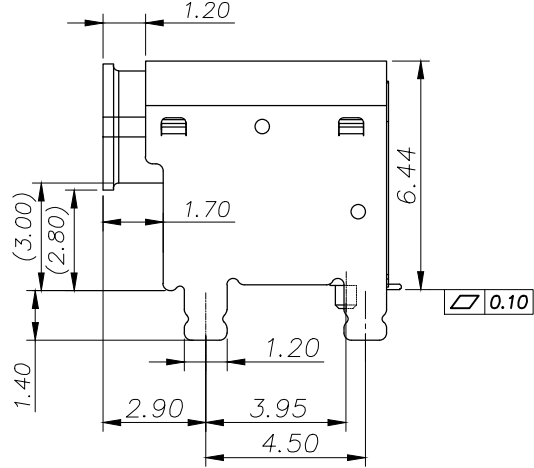
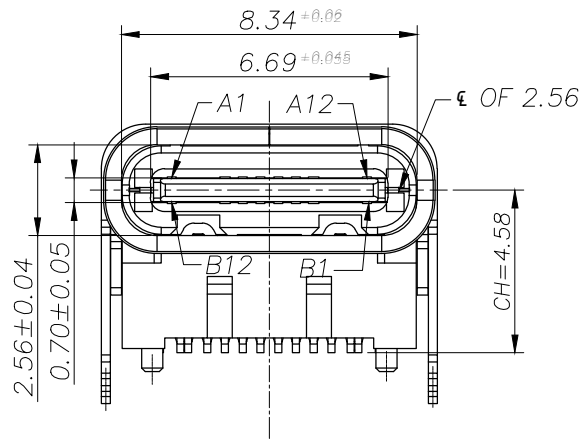
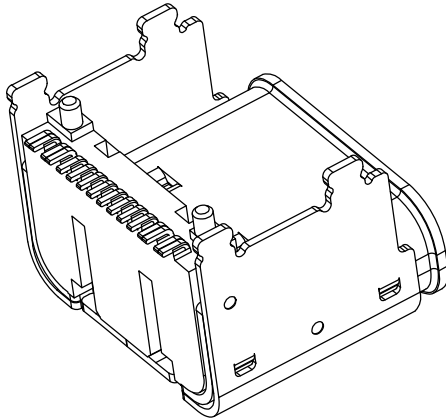
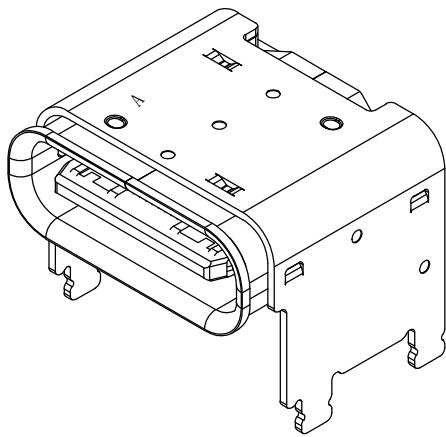
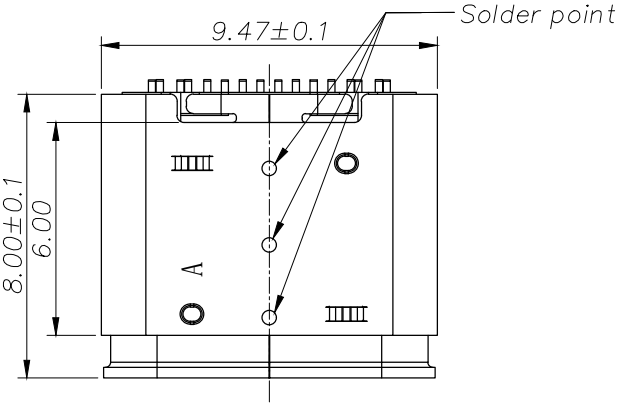
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审核
CHECKED

夏操云

批准
APPROVE

赵亮亮



AFTER MATING
SCALE 1:1

